

Title (en)

TIGHTNESS TEST FOR MEMS OR FOR SMALL ENCAPSULATED COMPONENTS

Title (de)

DICHTHEITSPRÜFUNG FÜR MEMS ODER KLEINE VERKAPSELTE KOMPONENTEN

Title (fr)

TEST DE L'ETANCHEITE DE MEMS OU DE PETITS COMPOSANTS ENCAPSULES

Publication

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Application

**EP 05782184 A 20050629**

Priority

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- FR 0451370 A 20040630

Abstract (en)

[origin: WO2006008412A1] The invention relates to a method for testing the tightness of a MEMS or of a small encapsulated component, the MEMS or small component being mounted in a cavity of a support. Said cavity is closed by sealing means and contains a gas having a density different than that if it were at the pressure of the medium outside of the cavity. The method comprises a step for measuring the density of the gas contained inside the cavity.

IPC 8 full level

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CPC (source: EP US)

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